



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR DPAK (TO-252), IPAK (HVM)					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	40	20 000	200 °C + N2	0	0.00
HAST	1120	112 000	130 °C, 85 % RH	0	0.00
Power Cycle	160	2 400 000	DELTA T _j = 100 °C	0	0.00
Pressure Pot	1200	120 000	121°, 15 PSIG	0	0.00
Solder DUNK	180	540	260 °C, 10 s	0	0.00
Solderability	30	30	883 M2003	0	0.00
Temp. Cycle	1120	880 000	-55 °C to 150 °C	0	0.00